



# International Symposium on Hybrid PICs at ECOC 2018 in Rome

Wednesday, September 26, 2018

9:30 – 17:00

Room SC2-A

organized by Fraunhofer HHI and Berlin Partner, Cluster Photonics

**Hybrid photonic integration enables the development of high-performance components that are complex and cost-effective at the same time.**

**This symposium covers the complete process chain from materials via simulation and fabrication to final assembly and showcases applications of hybrid PICs in communications and analytics.**

## PROGRAM

Chair: Hercules Avramopoulos, ICCS/NTUA, Greece

<b>09:30 – 10:00</b>	<b>Registration</b>
<b>10:00 – 11:00</b>	<b>Key note and Session 1: Materials</b> The future is plastics: polymer based hybrid integration for communication and sensing <i>Martin Schell, Fraunhofer HHI, Germany</i> Organic inorganic hybrid materials for PIC technology <i>Hideyuki Nawata, Nissan Chemical Industries Ltd., Japan</i> Free optical wiring for PIC with polymer realized with the Mosquito method <i>Takaaki Ishigure, Keio University, Japan</i>
<b>11:00 – 11:30</b>	<b>Coffee break</b>
<b>11:30 – 12:30</b>	<b>Session 2: Technologies</b> Polymer PICs: technology and prospects <i>Michael Lebbby, Lightwave Logic Inc., USA</i> Silicon-organic hybrid (SOH) integration and hybrid multi-chip systems: extending the capabilities of the silicon photonic platform <i>Christian Koos, Karlsruhe Institute of Technology / Vanguard Photonics GmbH, Germany</i> Automated assembly and testing of hybrid PICs: targeting high volume manufacturing needs <i>Ignazio Piacentini, ficonTEC GmbH, Germany</i>
<b>12:30 – 13:30</b>	<b>Lunch break</b>
<b>13:30 – 15:00</b>	<b>Session 3: Platforms</b> Silicon Nitride hybrid integration: technology and application <i>Arne Leinse, LioniX International BV, The Netherlands</i> Hybrid PolyBoard to TriPleX integration for next generation communication and sensing systems <i>Christos Kouloumentas, ICCS/NTUA / Optagon Photonics, Greece</i> The role of circuit simulations for the design of hybrid PICs <i>André Richter, VPIphotonics GmbH, Germany</i> Photonic integration at the quantum age – what challenges lie ahead? <i>Bernhard Schrenk, AIT Austrian Institute of Technology GmbH, Austria</i>
<b>15:00 – 15:30</b>	<b>Coffee break</b>
<b>15:30 – 17:00</b>	<b>Session 4: Applications</b> Polymeric devices for terahertz communications <i>Tadao Nagatsuma, Osaka University, Japan</i> Millimeter-wave photonic integrated circuits: from monolithic to heterogeneous to hybrid <i>Guillermo Carpintero, Universidad Carlos III de Madrid, Spain</i> Versatility of hybrid integration: from sensing to data centers <i>Milan Mashanovitch, Freedom Photonics LLC, USA</i> Addressing datacenter challenges with hybrid PICs <i>Paraskevas Bakopoulos, Mellanox Technologies Ltd., Israel</i>
<b>17:00</b>	<b>End of symposium – fairground closing</b>

The official conference language is English.

No attendance fee will be charged but please kindly [register](#). You can only enter with an ECOC badge.

### Venue:

ECOC 2018 – Fiera Roma  
Room SC2-A

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